

REMARKS

Favorable reconsideration of this application is respectfully requested in view of the following remarks.

By this Amendment, the Abstract and Claim 7 are amended, Claims 12-17 are added, and Claims 1-6 and 8-11 are canceled without prejudice to or disclaimer of the subject matter recited therein. Thus, Claims 7 and 12-17 are pending in this application. Claim 7 is the only pending independent claim. Applicant reserves the right to file a divisional application to pursue the subject matter of canceled Claims 1-6 and 11. Support for the new claims can be found, for example, on page 9, line 20 to page 10, line 24 of the specification. No new matter is added.

Examiner Kashnikow is kindly thanked for pointing out, on pages 2 and 3 of the Official Action, informalities in the Abstract. The Abstract is amended to correct the informalities. Thus, withdrawal of the objection to the Abstract is respectfully requested.

The rejections of canceled Claims 8-10 are moot.

The Official Action rejects independent Claim 7 under 35 U.S.C. §103(a) over U.S. Patent No. 6,044,628 to Katayama et al. ("Katayama") in view of U.S. Patent No. 4,264,668 to Balla.

Claim 7 recites a process of producing a web-form laminated material used for packaging containers comprising at least a support layer and a thermoplastic innermost layer. The process includes, *inter alia*, printing a conductive layer of a conductive composition containing a metal conductive filler to the inner surface of the support layer directly or indirectly only at zones where heat-sealing is conducted by high-frequency induction heating for forming a container.

Katayama discloses a method for producing a packaging container by which a plate-like web is molded to a tubular web, and contents such as fluid food are filled in the tubular web (see col. 1, lines 8-13). The Official Action acknowledges that Katayama fails to disclose the claimed printing step, but takes the position that it would have been obvious in light of Balla to modify Katayama's method to include printing a conductive composition layer.

Balla discloses a laminated material including an outer sealing layer of thermoplastic material and a second layer adjoining the thermoplastic layer. Balla discloses that the second layer includes carbon black as the conductive material and is adapted to be heated by a high-frequency electric field to transmit generated heat to the thermoplastic layer (see col. 1, lines 6-12 and col. 2, lines 10-14). The Office Action states that the carbon black corresponds to the claimed conductive filler. The Office Action further states that one skilled in the art it would have found it obvious to modify the method described in Katayama by applying carbon black as a conductive filler in selected areas of the packaging material.

However, Balla discloses that the resistivity of carbon black is preferably in the range of 0.1-1.0 ohm-cm (see col. 1, lines 55-59). On the other hand, the resistivity of an aluminum foil layer, such as disclosed by Katayama, is approximately 0.0000028 ohm-cm. The relatively higher resistivity of Balla's carbon black reduces the amount of heat that would be generated to heat seal Katayama's packaging material as compared with the aluminum foil layer. Accordingly, one skilled in the art would not have desired to modify Katayama's method to use Balla's carbon black as the conductive heater because doing so would have reduced the amount of heat generated to heat seal the packaging material. Thus, it would not

have been obvious to one skilled in the art to have modified Katayama's method as set forth by the Official Action.

In addition, carbon black is not a metal. Thus, Balla fails to disclose printing a conductive layer of a conductive composition containing a *metal* conductive filler as recited in independent Claim 7.

Therefore, the combination of Katayama and Balla does not disclose, and would not have rendered obvious, in combination with the other claimed elements, printing a conductive layer of a conductive composition containing a metal conductive filler to the inner surface of the support layer directly or indirectly only at zones where heat-sealing is conducted by high-frequency induction heating for forming a container as recited in independent Claim 7. Thus, withdrawal of the rejection is respectfully requested.

New Claims 12-17 are presented for consideration and further define the claimed conductive composition. These claims are patentable over the combination of Katayama and Balla at least by virtue of their dependence from patentable independent Claim 7, as well as for the additional aspects of the claimed process these claims recite.


Should any questions arise in connection with this application or should the Examiner believe that a telephone conference with the undersigned would be helpful in resolving any remaining issues pertaining to this application the undersigned respectfully requests that he be contacted at the number indicated below.

Respectfully submitted,

BUCHANAN INGERSOLL & ROONEY PC

Date: February 17, 2009

By:



Matthew L. Schneider
Registration No. 32814

David R. Kemeny
Registration No. 57241

P.O. Box 1404
Alexandria, VA 22313-1404
703 836 6620